

87224-1 ✓ ACTIVE

AMPMODU | AMPMODU Headers

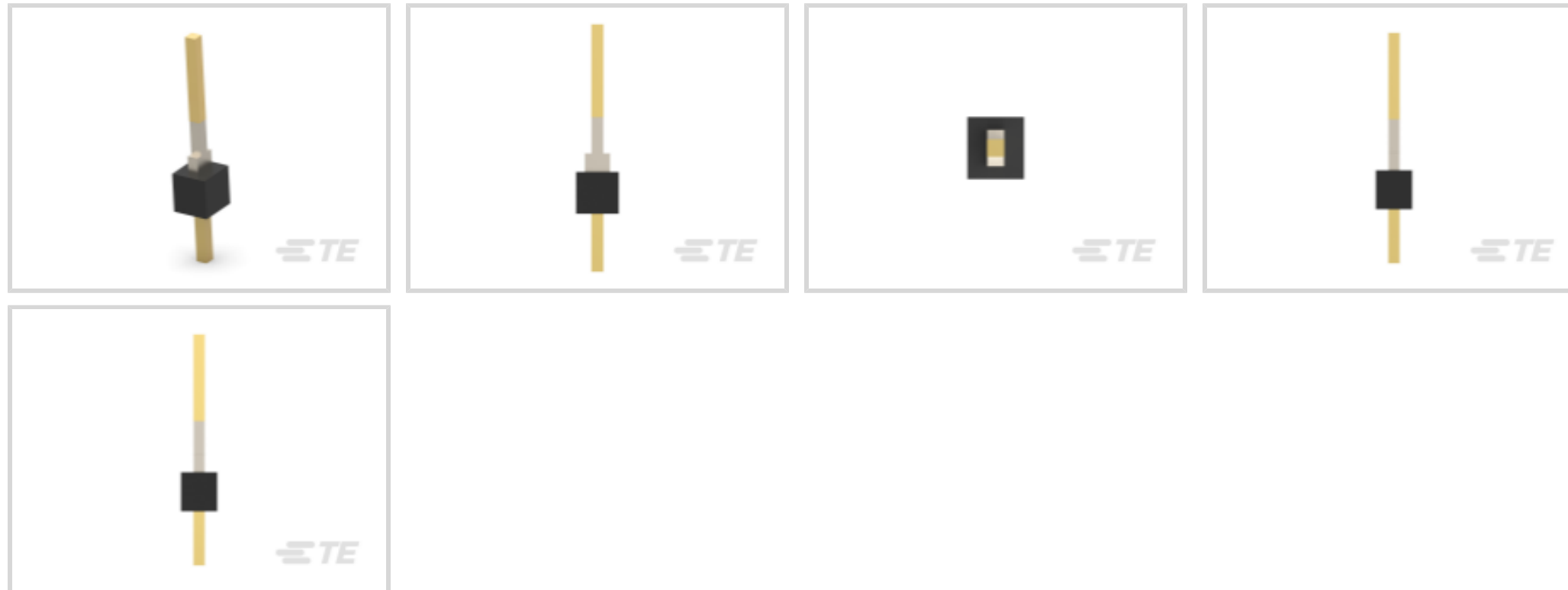
TE Internal #: 87224-1

PCB Mount Header, Vertical, Board-to-Board, 1 Position, 2.54 mm [.1 in] Centerline, Unshrouded, Gold, Through Hole - Solder, Signal, AMPMODU Headers

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Connectors > PCB Connectors > PCB Headers & Receptacles



PCB Connector Assembly Type: **PCB Mount Header**

PCB Mount Orientation: **Vertical**

Connector System: **Board-to-Board**

Number of Positions: **1**

Number of Rows: **1**

Features

Product Type Features

| | |
|-----------------------------------|-----------------------|
| PCB Connector Assembly Type | PCB Mount Header |
| Connector System | Board-to-Board |
| Header Type | Unshrouded |
| Sealable | No |
| Connector & Contact Terminates To | Printed Circuit Board |

Configuration Features

| | |
|----------------------------------|--------------|
| Connector Contact Load Condition | Fully Loaded |
| PCB Mount Orientation | Vertical |
| Number of Positions | 1 |
| Number of Rows | 1 |
| Board-to-Board Configuration | Parallel |

Electrical Characteristics

| | |
|---------------------------------------|----------|
| Insulation Resistance | 5000 MΩ |
| Dielectric Withstanding Voltage (Max) | 750 Vrms |



Body Features

| | |
|-----------------------|-------|
| Primary Product Color | Black |
|-----------------------|-------|

Contact Features

| | |
|--|--------------------------|
| Mating Square Post Dimension | .64 mm[.025 in] |
| Contact Shape & Form | Square |
| Contact Underplating Material | Nickel |
| PCB Contact Termination Area Plating Material | Gold Flash |
| Contact Base Material | Phosphor Bronze |
| Contact Mating Area Plating Material | Gold |
| Contact Mating Area Plating Material Thickness | .38 μ m[15 μ in] |
| Contact Type | Pin |
| Contact Current Rating (Max) | 3 A |

Termination Features

| | |
|---|-----------------------|
| Square Termination Post & Tail Dimension | .64 mm[.025 in] |
| Termination Post & Tail Length | 3.18 mm[.125 in] |
| Termination Method to Printed Circuit Board | Through Hole - Solder |

Mechanical Attachment

| | |
|-------------------------|-------------|
| Mating Alignment | Without |
| PCB Mount Retention | Without |
| PCB Mount Alignment | Without |
| Connector Mounting Type | Board Mount |

Housing Features

| | |
|--------------------|----------------|
| Centerline (Pitch) | 2.54 mm[.1 in] |
| Housing Material | Thermoplastic |

Dimensions

| | |
|-----------------------------|-----------------|
| PCB Thickness (Recommended) | 1.4 mm[.055 in] |
|-----------------------------|-----------------|

Usage Conditions

| | |
|-----------------------------|----------------------------|
| Housing Temperature Rating | Standard |
| Operating Temperature Range | -55 – 125 °C[-67 – 257 °F] |

Operation/Application

| | |
|---------------------|--------|
| Circuit Application | Signal |
|---------------------|--------|



Industry Standards

| | |
|------------------------|-----------------------|
| UL Rating | Recognized |
| Agency/Standard | CSA, UL |
| Approved Standards | CSA LR7189, UL E28476 |
| UL Flammability Rating | UL 94V-0 |

Packaging Features

| | |
|--------------------|--------|
| Packaging Quantity | 520 |
| Packaging Type | Carton |

Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

| | |
|---|---|
| EU RoHS Directive 2011/65/EU | Compliant |
| EU ELV Directive 2000/53/EC | Compliant |
| China RoHS 2 Directive MIIT Order No 32, 2016 | No Restricted Materials Above Threshold |
| EU REACH Regulation (EC) No. 1907/2006 | Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JUNE 2023 (235) Does not contain REACH SVHC |
| Halogen Content | BFR/CFR/PVC Free, but Br/Cl >900 ppm in other sources. |
| Solder Process Capability | Wave solder capable to 240°C |

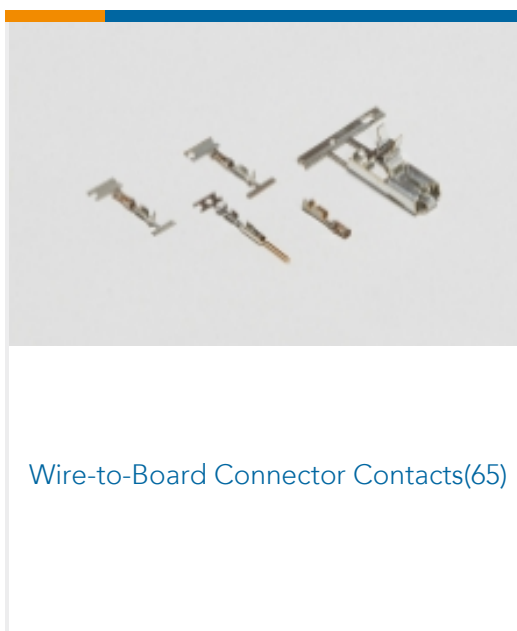
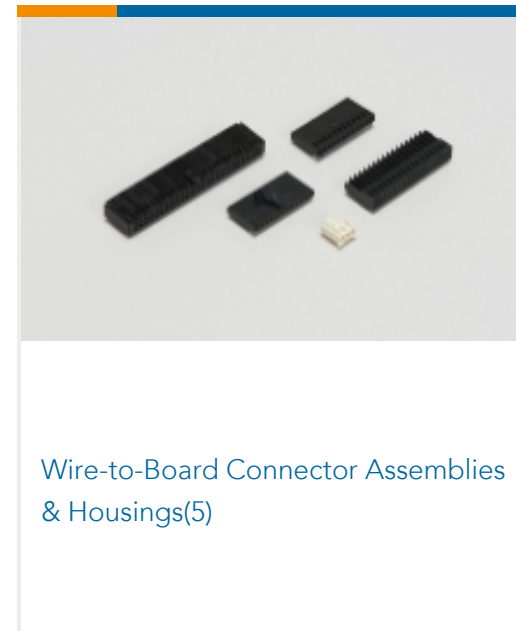
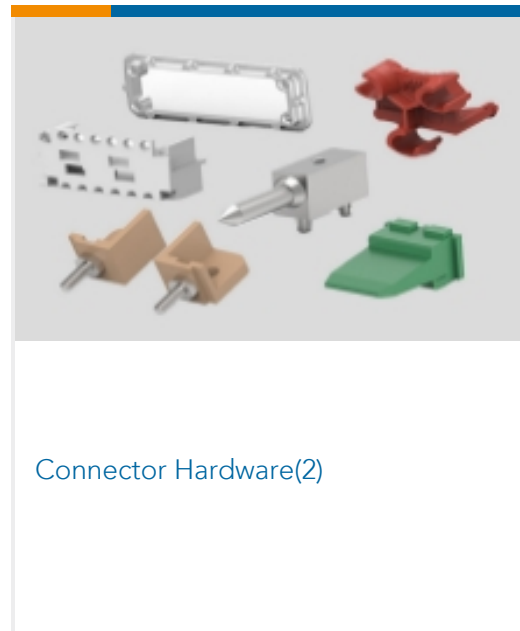
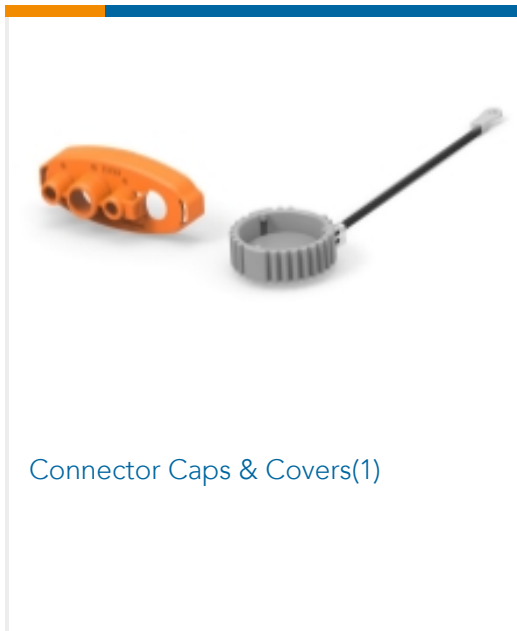
Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

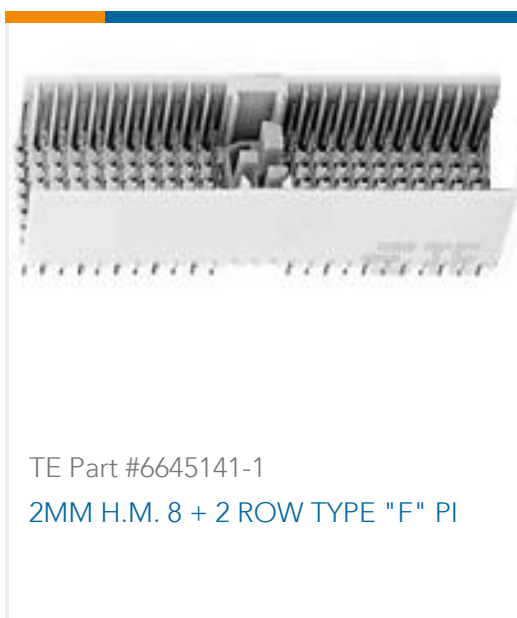
Compatible Parts



Also in the Series | AMPMODU Headers



Customers Also Bought





Documents

Product Drawings

[01 MODII HDR SRST UNSHRD .100](#)

English

CAD Files

Customer View Model

[ENG_CVM_87224-1_L.3d_igs.zip](#)

English

Customer View Model

[ENG_CVM_87224-1_L.2d_dxf.zip](#)

English

3D PDF

English

Customer View Model

[ENG_CVM_87224-1_L.3d_stp.zip](#)

English

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.

Datasheets & Catalog Pages

[AMPMODU_INTERCONNECTION_SYSTEM_SECTION5](#)

English

Product Environmental Compliance

[MD_87224-1_0221201846_dmtec](#)

English

[MD_87224-1_0221201846_dmtec](#)

English